**Product data sheet** 

# 1. General description

Planar passivated high commutation three quadrant triac in a TO220 plastic package. This "series E" triac balances the requirements of commutation performance and gate sensitivity and is intended for interfacing with low power drivers including microcontrollers.

### 2. Features and benefits

- · 3Q technology for improved noise immunity
- · Direct interfacing with low power drivers and microcontrollers
- · Good immunity to false turn-on by dV/dt
- · High commutation capability with very sensitive gate
- High voltage capability
- · Planar passivated for voltage ruggedness and reliability
- · Sensitive gate for easy logic level triggering
- Triggering in three quadrants only

### 3. Applications

- Electronic thermostats (heating and cooling)
- Motor controls e.g. washing machines and vacuum cleaners
- · Refrigeration and air-conditioner compressor controls

#### 4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	neter Conditions					Unit
Absolute	maximum rating						
$V_{DRM}$	repetitive peak off-state voltage			-	-	600	V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; T <sub>mb</sub> ≤ 106 °C; <u>Fig. 1;</u> <u>Fig. 2; Fig. 3</u>		-	-	10	А
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 20 ms; Fig. 4; Fig. 5		-	-	85	Α
		full sine wave; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 16.7 \text{ ms}$		-	-	93	А
T <sub>j</sub>	junction temperature			-	-	125	°C
Static ch	aracteristics			,			
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G+;$ $T_j = 25 \text{ °C; } Fig. 7$		0.5	-	10	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + \text{ G-;}$ $T_j = 25 \text{ °C; } Fig. 7$		0.5	-	10	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2-\text{ G-;}$ $T_j = 25 \text{ °C; } \underline{\text{Fig. 7}}$		0.5	-	10	mA

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	15	mA
V <sub>T</sub>	on-state voltage	I <sub>τ</sub> = 12 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.25	1.5	V
Dynamic	characteristics					
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 402 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	50	-	-	V/µs
dI <sub>com</sub> /dt	rate of change of commutating current	$V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 10 A; $dV_{com}/dt$ = 20 V/ $\mu$ s; (snubberless condition); gate open circuit	2	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 125 ^{\circ}\text{C}; I_{T(RMS)} = 10 \text{ A};$ $dV_{com}/dt = 10 \text{ V/}\mu\text{s}; gate open circuit}$	3	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 125 ^{\circ}\text{C}; I_{T(RMS)} = 10 \text{ A};$ $dV_{com}/dt = 1 \text{ V}/\mu\text{s}; gate open circuit}$	6	-	-	A/ms

# 5. Pinning information

### **Table 2. Pinning information**

	Simplified outline	Graphic symbol
in terminal 1	mb	N
in terminal 2	705	T2 — T1
te		G sym051
unting base; main terminal 2	<u> </u>	
iir	n terminal 2	n terminal 2

# 6. Ordering information

#### **Table 3. Ordering information**

Type number	Package name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BTA310-600E	TO220	BTA310-600E,127	Tube	50	SOT78	13-Jun-2008

# 7. Marking

### **Table 4. Marking codes**

Type number	Marking codes		
	Assembly factory: d	Assembly factory: A	
BTA310-600E	BTA310 600E PJdxxxx xx	BTA310 600E PJAxxxx xx	

# 8. Limiting values

### **Table 5. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage		-	600	V
I <sub>T(RMS)</sub>	RMS on-state current	full sine wave; T <sub>mb</sub> ≤ 106 °C; <u>Fig 1</u> ; <u>Fig 2</u> ; <u>Fig 3</u>	-	10	А
I <sub>TSM</sub>	non-repetitive peak on- state current	full sine wave; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 20 \text{ ms}$ ; Fig 4; Fig 5	-	85	А
		full sine wave; $T_{j(init)}$ = 25 °C; $t_p$ = 16.7 ms	-	93	А
l <sup>2</sup> t	I <sup>2</sup> t for fusing	t <sub>p</sub> = 10 ms; sine-wave pulse	-	36.1	A <sup>2</sup> s
dl <sub>⊤</sub> /dt	rate of rise of on-state current	I <sub>G</sub> = 0.2 A	-	100	A/µs
I <sub>GM</sub>	peak gate current		-	2	А
$P_{GM}$	peak gate power		-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	0.5	W
T <sub>stg</sub>	storage temperature		-40	150	°C
T <sub>j</sub>	junction temperature		-	125	°C

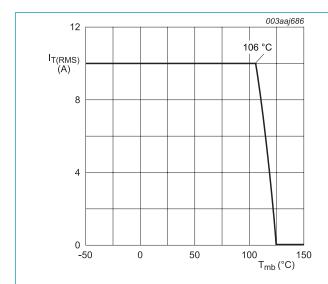
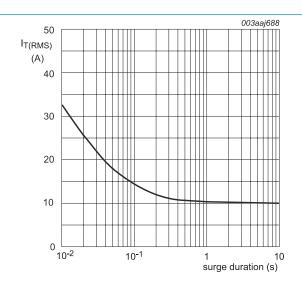
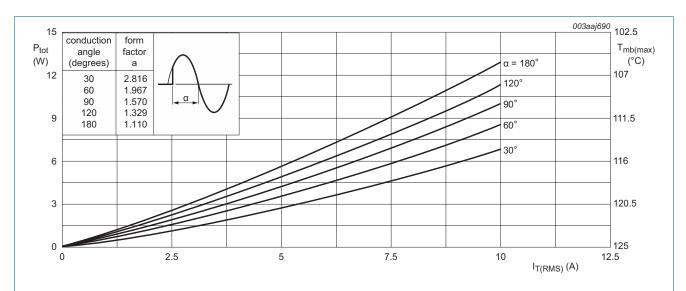


Fig. 1. RMS on-state current as a function of mounting base temperature; maximum values

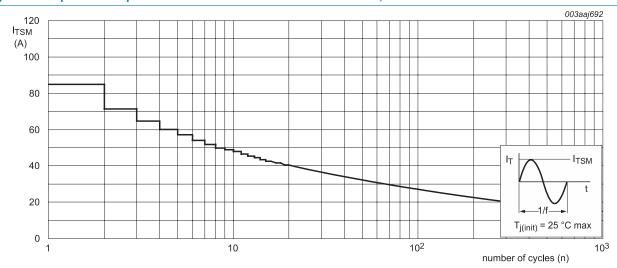


f = 50 Hz; T<sub>mb</sub> = 106 °C Fig. 2. RMS on-state current as a function of surge duration; maximum values



 $\alpha$  = conduction angle

 $a = form \ factor = I_{T(RMS)} / I_{T(AV)}$  Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

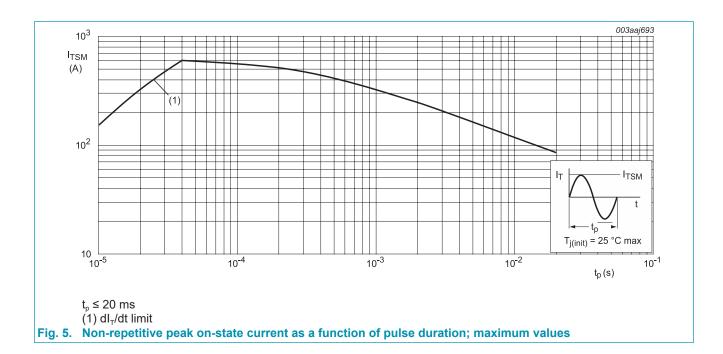


f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

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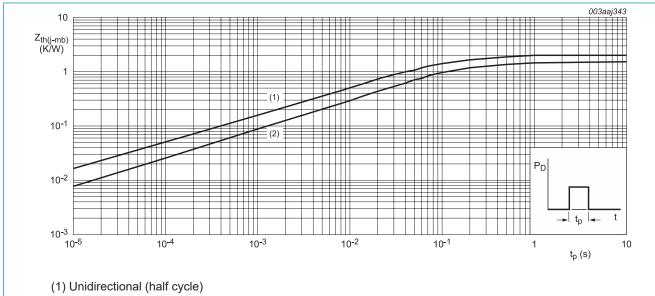
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# 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$R_{\text{th(j-mb)}}$	thermal resistance from junction to	full cycle; Fig 6	-	-	1.5	K/W
	mounting base	half cycle; <u>Fig 6</u>	-	-	2	K/W
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	in free air	-	60	-	K/W

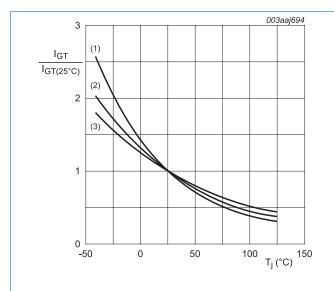


- (2) Bidirectional (full cycle)
- Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

# 10. Characteristics

**Table 7. Characteristics** 

<b>Symbol</b>	Parameter	Conditions	Min	Тур	Max	Unit
Static ch	aracteristics		·			
I <sub>GT</sub>	gate trigger current	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2 + G+;$ $T_j = 25 \text{ °C; } Fig. 7$	0.5	-	10	mA
		$V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T2+ G-;$ $T_j = 25 \text{ °C}; Fig. 7$	0.5	-	10	mA
		$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T2- \text{ G-;} $ $T_j = 25 \text{ °C; } Fig. 7$	0.5	-	10	mA
I <sub>L</sub>	latching current	V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <u>Fig. 8</u>	-	-	25	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; <u>Fig. 8</u>	-	-	30	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <u>Fig. 8</u>	-	-	25	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>	-	-	15	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 12 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>	-	1.25	1.5	V
V <sub>GT</sub>	gate trigger voltage	$V_D = 12 \text{ V; } I_T = 0.1 \text{ A; } T_j = 25 \text{ °C;}$ Fig. 11	-	0.7	1	V
		$V_D = 400 \text{ V}; I_T = 0.1 \text{ A}; T_j = 125 ^{\circ}\text{C}$	0.25	0.4	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 600 V; T <sub>j</sub> = 125 °C	-	0.1	0.5	mA
Dynamic	characteristics		'		,	
dV <sub>D</sub> /dt	rate of rise of off-state voltage	$V_{DM}$ = 402 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit	50	-	-	V/µs
dI <sub>com</sub> /dt	rate of change of commutating current	$V_D$ = 400 V; $T_j$ = 125 °C; $I_{T(RMS)}$ = 10 A; $dV_{com}/dt$ = 20 V/ $\mu$ s; (snubberless condition); gate open circuit	2	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 125 \text{ °C}; I_{T(RMS)} = 10 \text{ A};$ $dV_{com}/dt = 10 \text{ V}/\mu\text{s}; gate open circuit}$	3	-	-	A/ms
		$V_D = 400 \text{ V}; T_j = 125 \text{ °C}; I_{T(RMS)} = 10 \text{ A};$ $dV_{com}/dt = 1 \text{ V}/\mu\text{s}; \text{ gate open circuit}$	6	-	-	A/ms



- (1) T2- G-
- (2) T2+ G-

-50

(3) T2+ G+

Fig. 7. Normalized gate trigger current as a function of

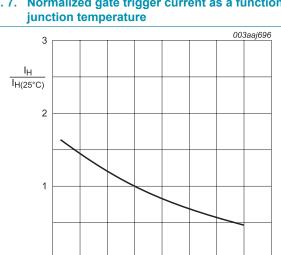


Fig. 9. Normalized holding current as a function of junction temperature

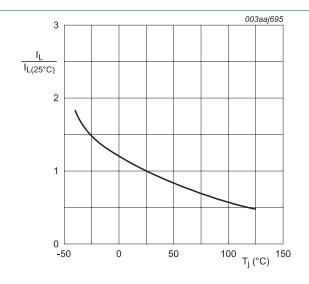
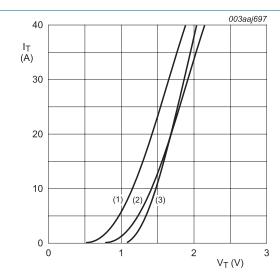


Fig. 8. Normalized latching current as a function of junction temperature



 $V_o = 1.103 \text{ V}; R_s = 0.030 \Omega$ 

(1) T<sub>j</sub> = 125 °C; typical values (2) T<sub>j</sub> = 125 °C; maximum values

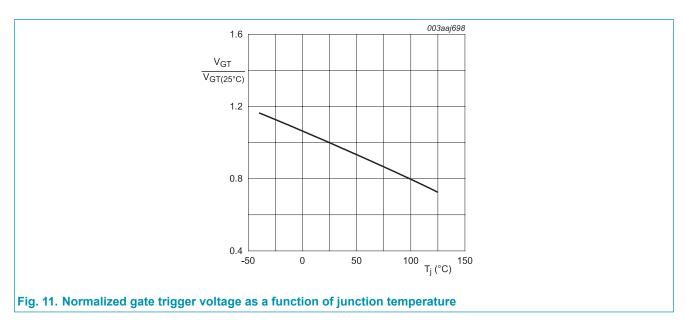
(3)  $T_j = 25$  °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

100 <sub>Ti</sub> (°C) 150

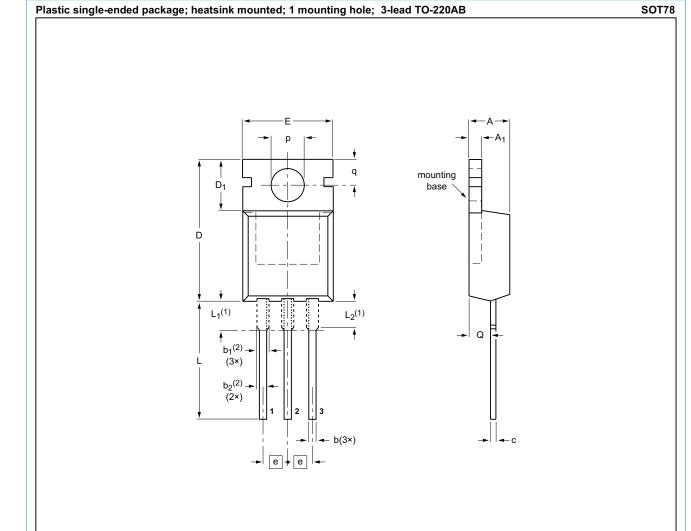
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# 11. Package outline

Assembly factory: d & A



# 0 5 10 mm scale

#### **DIMENSIONS** (mm are the original dimensions)

		-		-												
UNIT	Α	A <sub>1</sub>	b	b <sub>1</sub> <sup>(2)</sup>	b <sub>2</sub> (2)	С	D	D <sub>1</sub>	E	е	L	L <sub>1</sub> (1)	L <sub>2</sub> <sup>(1)</sup> max.	р	q	ď
mm	4.7 4.1	1.40 1.25	0.9 0.6	1.6 1.0	1.3 1.0	0.7 0.4	16.0 15.2	6.6 5.9	10.3 9.7	2.54	15.0 12.8	3.30 2.79	3.0	3.8 3.5	3.0 2.7	2.6 2.2

#### Notes

- Lead shoulder designs may vary.
   Dimension includes excess dambar.

	OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
	VERSION	IEC	JEDEC	JEITA	PROJECTION	ISSUE DATE
	SOT78		3-lead TO-220AB	SC-46		<del>08-04-23</del> 08-06-13

BTA310-600E

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#### Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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